

**AMENDMENTS TO THE SPECIFICATION**

Please amend the title as follows:

**~~METHOD AND STRUCTURE~~ FOR TEMPORARILY ISOLATING A DIE FROM  
A COMMON CONDUCTOR TO FACILITATE WAFER LEVEL TESTING**

Please substitute paragraph 7 beginning on page 3 with the following:

The present invention provides ~~a method and~~ an apparatus which facilitates temporary isolation of a die from one or more common conductors during wafer level testing. The one or more common conductors extend over a wafer and are connected to a plurality of dice on the wafers which are undergoing testing. A temporary isolation device (e.g., a diode, transistor or other element) is interposed between each die and the common conductor. The temporary isolation device can be used to isolate a die from the common conductor during wafer level testing whenever such isolation is needed.

Please amend the abstract as follows:

The invention provides ~~a method and~~ an apparatus for temporarily isolating a die from other dice on a wafer commonly connected to one or more common conductors. The conductors are connected to each die through a temporary isolation device, such as a diode. The common conductor supplies a signal to all dice during one set of test procedures, while the temporary isolation device can be used to isolate a die from the common conductor during another set of test procedures.